

BGS Attachment Method

Part Number: 2522B-EP04-BGS5

(Vis Number: 035810)

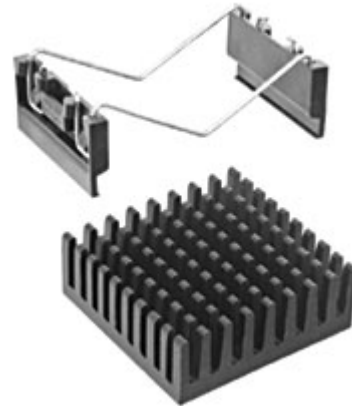
This part is in stock and available for immediate delivery:

Contact your [local sales rep](#)

BGA Surface	Interface	Heat Sink Finish	Part Class
All	EP04	Black Anodize	A

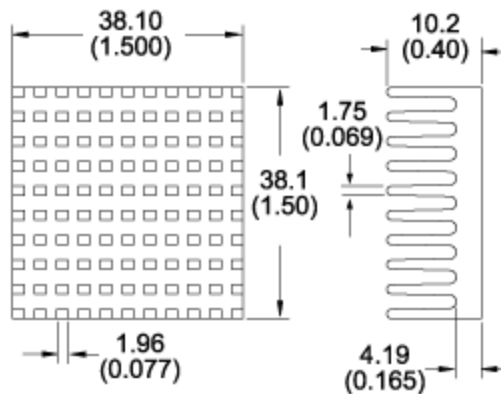
Features and Benefits

- A unique clip eliminates the need for mounting holes in the PC Board
- The clips unique design eliminates the need for thermal tape attachment
- The clips are available in industry standard sizes to fit a wide variety of BGA package sizes
- Each Heat Sink utilizes a phase change pad as the interface for optimal performance
- Clips overhang BGA by 3.0 mm



Width	Length	Height	Fin Thickness Across Width	Fin Thickness Across Length	Base Thickness	# of fins across width	# of fins across length
38.1mm	38mm	10.2mm	1.7mm	1.96mm	4.19mm	10	11

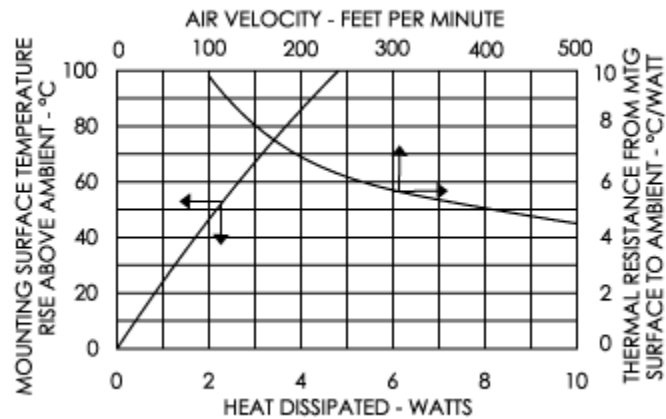
Mechanical Outline Drawing



Unless otherwise shown, tolerances are $\pm 0.38 (\pm 0.015)$

Thermal Performance

* θ_n	** θ_f
22.1	6.94



*Natural convection thermal resistance is based on a 75 °C heat sink temperature rise.

**Forced convection thermal resistance based on an entering 1.0 m/s (200 fpm) airflow.
Due to various heat dissipation paths within a BGA device, please test the heat sink in your application.

This data sheet represents only one of a broad range of products we make to cool electronics.
Our representatives can help you configure a complete cooling solution for your individual applications.

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